MITSUI
KINZOKU

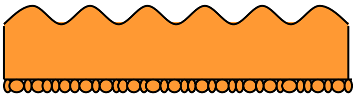
3EC-M1S-VLP

- 無載體箔之7μm薄銅箔，具高抗張力特性。
  Thin foil (7μm), high tensile strenght, supply without carrier foil.
- 極低粗糙度電解銅箔，適用於極細線路蝕刻之減成法製程。
  Low profile copper foil, suitable for fine etching in the subtractive process.

用途/Application

・軟性電路板
/Flexible Print Board

構成/Composition



生產地點/Production Site

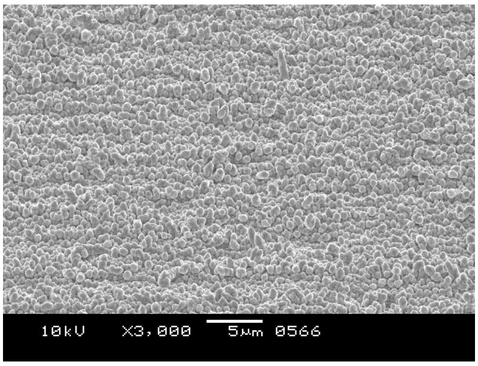
・日本/Japan

代表性特性數據/Representive

	μm	Laminate side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
3EC-M1S-VLP	7	1.8	500	4	0.7

※上述表列為代表性數據非保証值
This is representative date, not guarantee.

處理面/Laminate side



阻劑面/ resist side